

# N-Channel 150-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
150	0.030 at V <sub>GS</sub> = 10 V	50		
	0.033 at V <sub>GS</sub> = 6 V	45		

## **FEATURES**

- Trench Power MOSFETs
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC



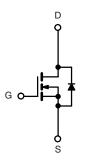
#### TO-262



Top View

## **APPLICATIONS**

· Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	150		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	1-	50		
Continuous Diain Current (1) = 175 C)	T <sub>C</sub> = 125 °C		35		
Pulsed Drain Current	I <sub>DM</sub>	150	A		
Avalanche Current		I <sub>AR</sub>			50
Repetitive Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AR</sub>	80	mJ	
	T <sub>C</sub> = 25 °C	В	166 <sup>b</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	$ P_D$	3.75		
Operating Junction and Storage Temperature R	ange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount TO-263c)	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.9			

### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	150			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50		
		V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	80			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.030			
Due to Course On Otata Destatore a	В	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A		0.033		1 _	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C		0.076		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.100			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A	10			S	
Dynamic <sup>b</sup>	•			•			
Input Capacitance	C <sub>iss</sub>			2500		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		290			
Reverse Transfer Capacitance	C <sub>rss</sub>			190			
Gate Resistance	$R_{g}$			2		Ω	
Total Gate Charge <sup>c</sup>	$Q_g$			38	60		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$		13		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			13			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 75 \text{ V}, R_{L} = 1.80 \Omega$		130	200		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 40 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			90	140		
Source-Drain Diode Ratings and Cha	aracteristics 7	Γ <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	I <sub>S</sub>				40	_	
Pulsed Current	I <sub>SM</sub>				80	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			100	150	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 40 A, dl/dt = 100 A/μs		5	8	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.25	0.6	μС	

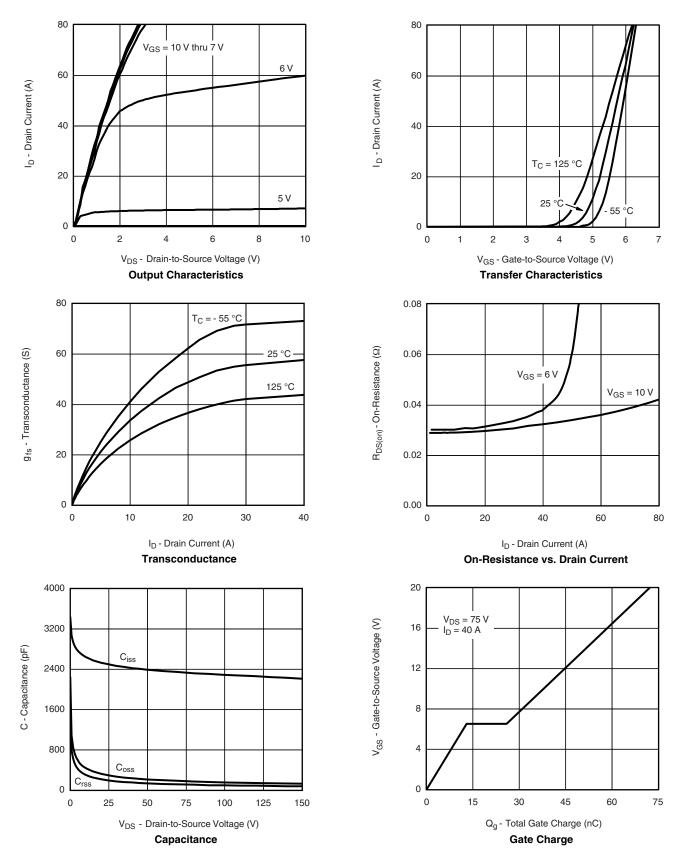
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

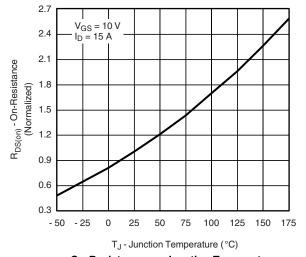


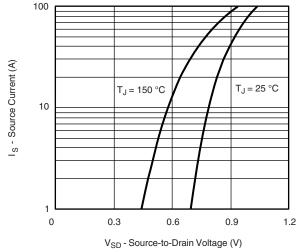
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





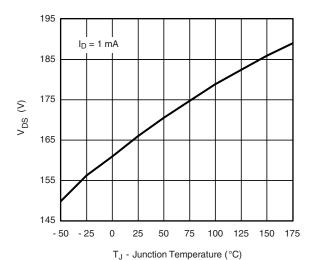
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On-Resistance vs. Junction Temperature

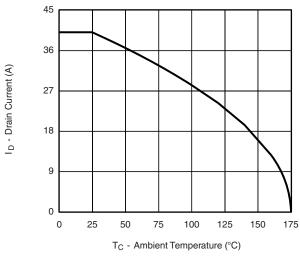
Source-Drain Diode Forward Voltage

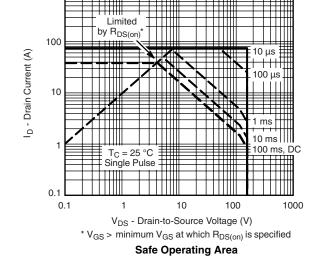


Drain Source Breakdown vs. Junction Temperature



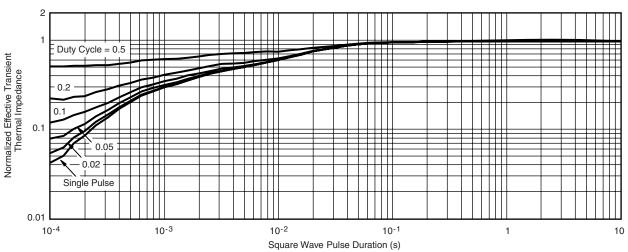
#### THERMAL RATINGS





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Maximum Avalanche and Drain Current vs. Case Temperature



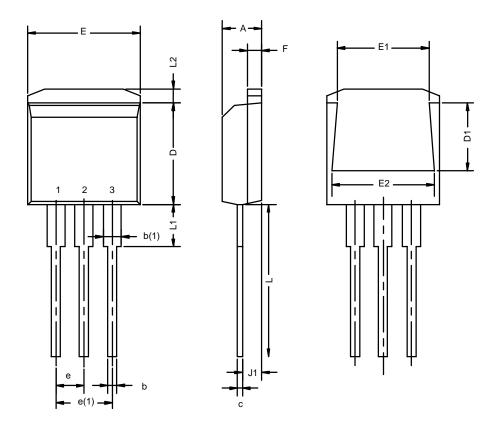
Normalized Thermal Transient Impedance, Junction-to-Case

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# TO-262: 3-LEAD



	MILLIMETERS*		INC	HES	
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
Е	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

<sup>\*</sup>Use millimeters as the primary measurement



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